# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3155507

| SUBMISSION TYPE:      | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |

### **CONVEYING PARTY DATA**

| Name                      | Execution Date |
|---------------------------|----------------|
| DIALOG SEMICONDUCTOR GMBH | 11/03/2014     |

### **RECEIVING PARTY DATA**

| Name:             | DIALOG SEMICONDUCTOR (UK) LIMITED |
|-------------------|-----------------------------------|
| Street Address:   | TOWER BRIDGE HOUSE                |
| Internal Address: | ST KATHARINE'S WAY                |
| City:             | LONDON                            |
| State/Country:    | UNITED KINGDOM                    |
| Postal Code:      | E1W 1AA                           |

## **PROPERTY NUMBERS Total: 4**

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 14453689 |
| Application Number: | 14491001 |
| Application Number: | 14445288 |
| Application Number: | 14445300 |

### **CORRESPONDENCE DATA**

**Fax Number:** (845)471-2064

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Email:debbi@saileackerman.comCorrespondent Name:SAILE ACKERMAN LLCAddress Line 1:28 DAVIS AVENUE

Address Line 4: POUGHKEEPSIE, NEW YORK 12603

| ATTORNEY DOCKET NUMBER: | DS GMBH>LTD        |
|-------------------------|--------------------|
| NAME OF SUBMITTER:      | STEPHEN ACKERMAN   |
| SIGNATURE:              | /Stephen Ackerman/ |
| DATE SIGNED:            | 12/19/2014         |

# **Total Attachments: 4**

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> PATENT REEL: 034553 FRAME: 0902

### **CONFIRMATION AND ASSIGNMENT**

WHEREAS Dialog Semiconductor GmbH, a corporation organized under the laws of Germany, having a place of business at Neue Str. 95, 73230 Kirchheim, Germany, (the "ASSIGNOR") is the owner of certain rights, title and interest in and to certain inventions and designs (the "Inventions"); and

WHEREAS Dialog Semiconductor (UK) Limited is a corporation organized under the laws of the United Kingdom, having a place of business at Tower Bridge House, St Katharine's Way, London E1W 1AA, United Kingdom, (the "ASSIGNEE"); and

WHEREAS ASSIGNOR wishes to confirm that ASSIGNEE is the owner of all rights, title and interest in and to certain of the Inventions, described in applications for patents, design registrations, utility model registrations and other forms of protection ("the Applications"), inclusive of any and all priority rights derived therefrom, and all ancillary rights relating thereto, as listed in Schedule "A" attached hereto.

NOW THEREFORE, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged by ASSIGNOR and ASSIGNEE, intending to be legally bound, agree as follows:

ASSIGNOR hereby confirms that it has transferred, conveyed and assigned, and by way of further assurance, to the extent that the transfer, conveyance or assignment has not already been fully effected, ASSIGNOR hereby transfers, conveys and assigns, any and all of its rights, title and interest in and to the Applications, inclusive of any and all priority rights, including the right to claim priority, derived from the Applications; all of its rights, title and interest in and to all Letters Patent to be obtained from the Inventions by the Applications, and as to Letters Patent any re-issue or re-examination thereof; together with the right to file divisional applications, substitute applications and continuation applications of any one or more of the Applications ("Divisionals");; with the intent that the Applications and Divisionals are owned and enjoyed by ASSIGNEE absolutely to the full end of the term or terms for same.

ASSIGNOR hereby agrees, upon request, to provide assistance and to execute any and all further documents which may be necessary or desirable to enable ASSIGNEE or its successors and assigns (as applicable), to file and prosecute the Applications and Divisionals, and to maintain, issue and enforce the Applications and all Letters Patent to be obtained from the Inventions by the Applications, and ASSIGNOR further agrees to execute, upon request, any and all further documents which may be necessary or desirable to vest or perfect the title of ASSIGNEE therein.

ASSIGNOR hereby authorizes and requests the respective patent office, or any equivalent authority, to issue to ASSIGNEE each and every patent, registration and other forms of protection, right and title granted upon the Applications and the Divisionals.

THIS ASSIGNMENT shall inure to the benefit of ASSIGNEE and its successors and assigns and shall be binding upon ASSIGNOR and its successors and permitted assigns.

IF ANY COVENANT OR PROVISION, or portion thereof, of this document is determined to be void or unenforceable, such void or unenforceable covenant or provision, or portion thereof, is hereby conceded to be severable from the balance of this document, and any such determination shall not, in any event, affect or impair the validity of the balance of the covenant or provision, nor shall it affect or impair the validity of any other covenant or provision herein contained.

IN WITNESS WHEREOF, this Confirmation And Assignment has been executed below by the undersigned on behalf of the Assignor:

|  | Dialog Sen             | niconductor GmbH                                |
|--|------------------------|---|
| Date: 3 11 14  | By:<br>Name:<br>Title: | Dr. Jalal Bagherli<br>CEO, Dialog Semiconductor |
| STATEMENT BY   |                        | ull Post Office Address is                      |
| HY NORTH STREET, EGHAM   | <del></del>            |   |
| (Address of W  |                        |   |
| hereby declare that I was personally present ar sign and execute the same. | •                      | e above named person duly                       |
| Date: 3/11/14  | XI                     | oruno   |

(Signature of Witness)

# SCHEDULE "A" to Confirmation and Assignment

| Application No. | Country | Filing date (priority date) | DS ref.     | MERH ref. | Applicant                  |
|-----------------|---------|-----------------------------|-------------|-----------|----------------------------|
| 14154970.9      | ΕP      | 2/13/2014                   | DS 2013-072 | 204918EP  | Dialog Semiconductor GmbH  |
| 14156029.9      | ЕP      | 2/20/2014                   | DS 2013-058 | 204936EP  | Dialog Semiconductor GmbH  |
| 14152342.3      | EP      | 1/23/2014                   | DS 2013-049 | 204948EP  | Dialog Semiconductor GmbH  |
| 14154877.6      | ΕP      | 2/12/2014                   | DS 2013-059 | 204961EP  | Dialog Semiconductor GmbH  |
| 14154743.0      | EP      | 2/11/2014                   | DS 2013-069 | 204989EP  | Dialog Semiconductor GmbH  |
| 14174562.0      | EP      | 6/26/2014                   | DS 2013-066 | 205084EP  | Dialog Semiconductor GmbH  |
| 14163462.6      | ЕÞ      | 4/3/2014                    | DS 2013-071 | 205100EP  | Dialog Semiconductor GmbH  |
| 14159330.1      | EP      | 3/13/2014                   | DS 2013-082 | 205101EP  | Dialog Semiconductor GmbH  |
| 14150649.3      | EP      | 1/9/2014                    | DS 2013-086 | 205136EP  | Dialog Semiconductor GmbH  |
| 14171088.9      | EP      | 6/4/2014                    | DS 2013-105 | 205154EP  | Dialog Semiconductor GmbH  |
| 14150665.9      | EP      | 1/9/2014                    | DS 2013-073 | 205171EP  | Dialog Semiconductor GmbH  |
|                 |         |                             |             |           | Dialog Semiconductor GmbH; |
| 14156019.3      | EP      | 2/20/2014                   | DS 2013-090 | 205277EP  | Dialog Semiconductor Inc.  |
| 14174395.5      | EP      | 6/26/2014                   | DS 2013-092 | 205318EP  | Dialog Semiconductor GmbH  |
| 14159329.3      | ЕP      | 3/13/2014                   | DS 2014-011 | 205394EP  | Dialog Semiconductor GmbH  |
| 102014212502.2  | DE      | 6/27/2014                   | DS 2014-008 | 205563    | Dialog Semiconductor GmbH  |
| 102014213963.5  | DE      | 7/17/2014                   | DS 2014-009 | 205634    | Dialog Semiconductor GmbH  |
| 14/453,689      | SU      | 07.08.2014 (23.01.2014)     | DS 2013-049 | 204948US  | Dialog Semiconductor GmbH  |
| 14/491,001      | US      | 19.09.2014 (03.04.2014)     | DS 2013-071 | 205100US  | Dialog Semiconductor GmbH  |
| 14/445,288      | US      | 29.07.2014 (09.01.2014)     | DS 2013-086 | 205136US  | Dialog Semiconductor GmbH  |
| 14/445,300      | US      | 29.07.2014 (09.01.2014)     | DS 2013-073 | 205171US  | Dialog Semiconductor GmbH  |

PATENT REEL: 034553 FRAME: 0906

RECORDED: 12/19/2014